



P/1929-47

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Yoshinobu KANEYAMA

Serial No.: 09/198,849

Filed: November 24, 1998

For: DEVICE MOUNTING METHOD

New York, New York

Date: June 27, 2000

Group Art Unit: 1725

Examiner: M. Elve

Asst. Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Office Action mailed March 28, 2000, please reconsider the above-identified application amended as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) A [mount] mounting method for joining a device to a substrate using solder [with soldering], characterized in that [joint] the joining of said device and said substrate [through solder] is performed while said device is at least partially submerged in a liquid, wherein said device is at least partially supported by a buoyant force.

2. (Amended) The [mount] mounting method as claimed in claim 1, wherein the [joint based on] joining of said substrate to said device using said solder is performed while [ultrasonic] a vibration is applied to said [solder through the liquid] device.

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